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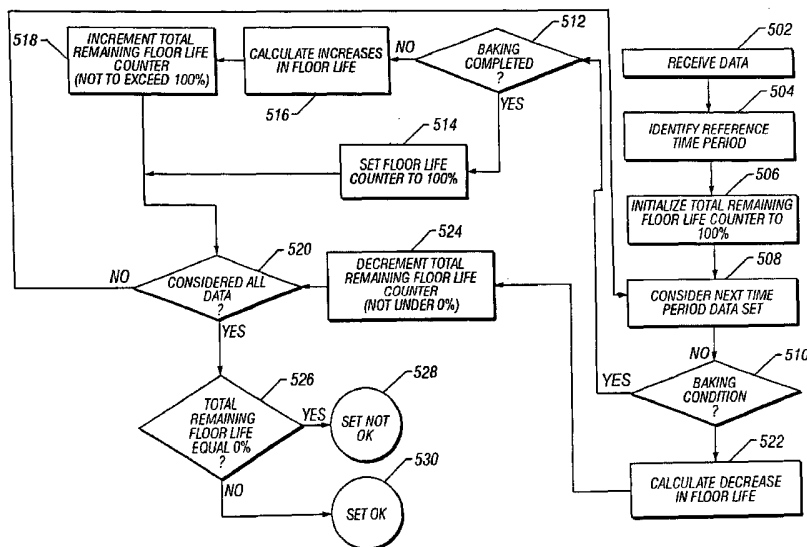
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[Continued on next page]

(54) Title: METHOD AND APPARATUS FOR EVALUATING A SET OF ELECTRONIC COMPONENTS



(57) Abstract: A method is disclosed of evaluating a set of identical electronic components prior to installing the components into electronic assemblies, including: collecting (102) data indicative of an environmental condition associated with the electronic components during consecutive periods of time prior to installing the electronic components from the set into the electronic assemblies, storing (104) the collected data and evaluating (106) whether the electronic components are suitable for installation based on an estimated cumulative effect of exposure to the environmental condition based on the stored data; and then, for electronic components found suitable for installation, installing the suitable electronic components into electronic assemblies.

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METHOD AND APPARATUS FOR EVALUATING A SET OF ELECTRONIC COMPONENTS

BACKGROUND

Manufacturers often handle a large number of electronic components when assembling
5 electronic devices. These electronic components can be susceptible to damage, especially during
printed circuit board manufacturing processes, as a result of prolonged exposure to environments
having high ambient moisture content. Ambient moisture can penetrate the bodies of moisture
sensitive components and become trapped. During certain manufacturing processes, such as
reflow, these electronic components are exposed to high temperatures. The high temperatures
10 can cause the trapped moisture to expand and can damage the electronic components.

To minimize the occurrence of such damage, electronic components can be baked at
elevated temperatures to remove at least some of the trapped moisture prior to reflow or
exposure to other high temperatures.

15 SUMMARY OF THE INVENTION

In one broad aspect, a method is disclosed of monitoring an environmental condition
associated with a container containing a set of electronic components. The method includes
attaching a moisture recorder to the container, the moisture recorder having a sensing element
responsive to atmospheric moisture content, a memory storage device, and a processor
20 electrically coupled to the sensing element and to the memory storage device. The processor is
configured to periodically receive information from the sensing element indicative of
atmospheric moisture content and to store data in the memory storage device based on the
received information.

In second broad aspect, a method is disclosed of evaluating a set of identical electronic components prior to installing the components into electronic assemblies. The method includes collecting data indicative of an environmental condition associated with the electronic components during multiple consecutive periods of time prior to installing the electronic components from the set into the electronic assemblies, storing the collected data and evaluating whether the electronic components are suitable for installation based on an estimated cumulative effect of exposure to the environmental condition based on the stored data.

In another broad aspect, a container of electronic components to be installed into electronic assemblies is disclosed that includes a storage device containing a set of electronic components and an environmental condition recorder coupled to the storage device and associated with the set of electronic components. The environmental condition recorder includes sensing elements responsive to an ambient environmental condition, a processor and an associated memory storage device. The processor is configured to receive data from the sensing elements indicative of the ambient environmental condition during multiple, successive periods of time, to cumulatively and accessibly store the data in the associated memory storage device and to evaluate whether the electronic components are suitable for installation based on a cumulative effect of exposure to the ambient environmental condition.

In yet another broad aspect, a system is disclosed for evaluating a set of identical electronic components prior to installing the components into electronic assemblies. The system includes a storage device containing a set of identical electronic components, an environmental condition recorder coupled to the storage device and associated with the set of identical electronic components and a remote device comprising a processor and a memory storage unit. The environmental condition recorder is configured to collect data indicative of an

environmental condition over multiple, successive periods of time and the processor is configured to receive the collected data from the environmental condition recorder and to evaluate whether the electronic components are suitable for installation based on the collected data.

5 In another broad aspect an article is disclosed that includes a computer-readable medium that stores computer executable instructions for causing a computer system to evaluate whether a set of electronic components are suitable for installation based on received time-based data representative of ambient moisture content associated with the set of electronic components.

In some implementations one or more of the following advantages may be present. The frequency of electronic component damage due to the expansion of trapped moisture during reflow and other manufacturing processes can be minimized. This can result in improved reliability of both electronic components and electronic assemblies.

An increase of available component historical data can enable users to make better informed decisions regarding whether to dry out electronic components prior to reflow. Consequently, the frequency of unnecessary baking can be decreased.

A better understanding of quality control management techniques can be developed and a subsequent manufacturing cost savings can be realized through improvements in manufacturing process efficiency.

Additionally, the collecting and interpreting of environmental data associated with electronic components prior to installation into an electronic assembly can be simplified.

Other features and advantages will be readily apparent from the following detailed description, the accompanying drawings and the claims.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a flow diagram for evaluating a set of electronic components.

FIGS. 2A and 2B illustrate system block diagrams for evaluating a set of electronic components.

5 FIGS. 3A through 3E illustrate techniques for coupling an environmental condition sensor to a set of electronic components.

FIG. 4 is a flow diagram for monitoring and evaluating a set of electronic components throughout assembly.

FIG. 5 provides environmental data represented graphically as a function of time.

10 FIG. 6A and 6B are flow diagrams for processing data to evaluate a set of electronic components.

FIG. 7 is a prior art table containing total floor life estimating data.

FIG. 8 is a prior art table containing data indicating baking conditions.

15 FIG. 9 provides an illustrative example of data represented graphically as a function of time.

DETAILED DESCRIPTION OF THE DRAWINGS

FIG. 1 outlines a method of evaluating a set of electronic components prior to installing any of the electronic components into an assembly. Such a set of components may include, for
20 example, identical electronic components contained within a shipping package, attached to a reel assembly or contained within a storage carton for future installation into an electronic assembly.

The method of evaluating these components includes collecting 102 data indicative of a potentially variable environmental condition, such as ambient moisture content, over a period of

time. Ambient moisture content may be sensed either directly or indirectly. For example, ambient moisture content may be measured directly as absolute humidity, expressed as a mass of water vapor in a given volume of air, commonly expressed in grams per cubic meter.

Alternatively, a determination of ambient moisture content can be made based on measured values of temperature and relative humidity. Other methods of measuring or determining ambient moisture content also may be used.

The variation of environmental conditions that a set of electronic components is exposed to can be attributed to transporting the set from one place to another, each place having a different ambient environmental condition. Alternatively, an environmental condition can change at a single location, such as at a storage facility. Although such facilities typically include environmental control systems to regulate critical environmental conditions, these systems can have limited control abilities. Also, these systems can be prone to failure, consequently exposing the set of electronic components to potentially undesirable environmental conditions for potentially unacceptable lengths of time.

The method of evaluating the set of electronic components also includes storing the collected data. Such storage of data can provide an indication of how a particular environmental condition varied over a length of time. Developing such an understanding can facilitate evaluating whether the set of electronic components can be expected to survive a printed circuit board assembly process and can therefore be considered to be suitable for installation.

The method also includes evaluating the suitability for installation of the associated electronic components into an assembly. The suitability for installation can be adversely impacted by exposure to ambient moisture. The evaluating can include, for example, estimating a remaining floor life associated with the set of electronic components. Remaining

floor life can be described as an estimated amount of time that a moisture sensitive device can be exposed to a given set of environmental conditions without being susceptible to subsequent damage, for example, during reflow. Remaining floor life can be cumulatively decremented over time.

5 The evaluating 106 also can include determining a cumulative environmental exposure factor. Such a cumulative environmental exposure factor might be an integral function of ambient temperature and relative humidity over time. Such a factor can provide an arbitrary indication of the potential suitability of a set of electronic components for use in a printed circuit board assembly process after exposure to potentially detrimental environmental conditions.

10 The evaluating 106 also could include determining a reliability index indicative of an expected reliability associated with the set of electronic components. Such a reliability index might be calculated by a proportional function including a calculated environmental exposure factor in the numerator and an arbitrary benchmark value representative of an ideal reliability in the denominator. This reliability index could be expressed, for example as a fraction, a decimal
15 or a percentage.

 The evaluating 106 also could include comparing a calculated value quantifying an expected reliability with an arbitrary minimum acceptable value to ascertain a go/no-go type of determination regarding whether a particular set of electronic components are suitable for installation into an assembly.

20 Referring now to the system 200 of FIG. 2A, the environmental condition recorder 202 includes a temperature-sensing element 204 responsive to ambient temperature and a relative humidity sensing element 206 responsive to ambient relative humidity. The sensing elements 204, 206 are responsive in real time. The environmental condition recorder 202 also includes an

integral processor 208, a memory storage unit 210 and a timing element 212, which may be part of the processor 208. The processor 208 is configured to receive periodically sampled data from the sensing elements 204, 206 and to store that data in the memory storage unit 210.

The environmental condition recorder 202 can be coupled to a remote device 214 through a communications channel 216. The remote device 214 could be, for example, a computer, a personal digital assistant (PDA), or a paging device that includes a processor 218 and a memory storage unit 220. The communications channel 216 could be, for example, a wireless communications channel.

The remote device 214 also is coupled to a memory storage device 222 through the communications channel 224. The memory storage device 222 can be, for example, a disk drive and can read instruction 226 for the remote device 214 stored on a computer readable medium, such as the disk 228. Alternatively, the memory storage device could be a flash memory unit.

The environmental condition recorder 202 can be coupled to a set of electronic components intended for eventual installation into an electronic assembly. The environmental condition recorder 202 can collect data indicative of an ambient environmental condition the associated set is exposed to. The processor 208 can perform local processing of the data. Alternatively, the environmental condition recorder 202 can transfer collected data to the remote device 214 for processing.

As shown in FIG. 2B, the functionality of the remote device's processor 218 and memory storage unit 220 could be incorporated into the local processor 208A and the memory storage unit 210A of the environmental condition recorder 202A. The environmental condition recorder 202A also includes an indicator 230, for example a light emitting diode (LED), to communicate positive/negative, go/no-go type data to a user examining the LED.

Referring to FIG. 3A, manufacturers of electronic components might attach an environmental condition recorder 202 to a reel 304 of electronic components inside a sealed compartment 302 for shipping. The environmental condition recorder 202 could be attached, for example, by using an adhesive material or by inserting the environmental condition recorder 202 into a storage pouch attached to the reel 304. The sealed compartment 302 can be used to ship and store either a reel 304 or several reels of electronic components.

Alternatively, a manufacturer might ship a reel 304 of electronic components in an airtight package 302 without an environmental condition recorder 202. In that case, the electronic assembly manufacturer might attach and reset an environmental condition recorder to the reel 304 of electronic components when the sealed package 302 is opened.

In certain embodiments, the environmental condition recorder 202 is a machine-readable computer chip in a stainless steel can 306 attached to a flange member 308 having an aperture 310. Each environmental condition recorder 202 has a unique identification number that can be read by an external machine. This unique identification number can be used as a unique identifier for the associated set of electronic components. The environmental condition recorder 202 also can be resettable.

Referring now to FIG. 3B, the reel 304 of electronic components can be removed from the sealed compartment 302 and be mounted on a reel-type electronic component feeder 312.

FIG. 3C illustrates a portable feeder bank 315 with two feeders 312 mounted in two of its slots. When the feeders 312 are mounted in their chosen slots, their associated environmental condition recorders 202 can be temporarily removed from each reel 304 and be placed in a corresponding reader 316 permanently mounted on the bank 315 adjacent each feeder slot. As the operator installs feeders 312 into the bank 315 to configure the bank 315 for a particular job,

he inserts the environmental condition recorder 202 into appropriate readers 316 on the bank 315. The configuration of the feeder bank 315 may be completed before the bank is brought to a placement machine for docking. When the bank is docked, the string of readers 316 can be connected for communication with other component banks and a system controller via end connectors 318. Such communications may be accomplished over other media, such as a computer network.

Each reader 316 defines a receptacle 320 for receiving the environmental condition recorder 202. Each reader 316 also has both male and female serial connectors, one at either end, such that the readers 316 may be mechanically connected in a serial string having but one male and one female serial connector 318 for communication with other reader strings and a host computer. Each reader 316 contains a microprocessor (not shown) for reading the chip embedded within the environmental condition recorder 202. A reader 316 typically can be positioned anywhere on a feeder 312 or on a bank 315.

After installation of electronic components from the reel 304 into electronic assemblies, if there are still electronic components remaining on the reel 304, the environmental condition recorder 202 can be reattached to the reel 304, which can then be placed back into storage. Alternatively, if all electronic components of the reel 304 have been used, the environmental condition recorder 202 can be reset and subsequently be attached to a different set of electronic components. Resetting an environmental condition recorder 202 can include erasing its memory.

FIG. 3D illustrates a storage bin 322 with an environmental condition recorder 202 secured to it. The storage bin 322 contains a set 324 of discreet electronic components, and might be used at a factory or warehouse to store discreet components, sealed compartments 302 containing electronic components or reels 304 of electronic components. The environmental

condition recorder 202 can be permanently attached to the storage bin 322 or removably attached using, for example, an adhesive.

FIG. 3E shows a tray 326 of identical electronic components. An environmental condition recorder 202 is coupled to the tray. This coupling can be accomplished through the use of, for example, an adhesive or a clip connection.

Referring now to FIG. 4, a method of monitoring an environmental condition associated with a container containing a set of electronic components is described that includes attaching an environmental condition recorder to the container. The environmental condition recorder can include a sensing element responsive to atmospheric moisture content, a memory storage device, and a processor electrically coupled to the sensing element and the memory storage device. The processor can be configured to periodically receive information from the sensing element indicative of atmospheric moisture content and to store data in the memory storage device based on the received information. The container and the attached environmental condition recorder can be transported from a storage area to an assembly station where at least some of the electronic components can be installed into electronic assemblies. At the assembly station, the data stored in the memory storage device is accessed by a memory reader at the assembly station. The memory reader at the assembly station can evaluate whether electronic components of the set of electronic components are suitable for installation into the electronic assemblies, based on the data accessed by the memory reader. A portion of the set of electronic components can be removed from the container for installation into the electronic assemblies at the assembly station. Then, the container with a remaining portion of the set of electronic components and the attached environmental condition recorder is transported from the assembly station to the storage area.

FIG. 5 illustrates a graphical representation of environmental condition measurements recorded by an environmental condition recorder 202 over time. The processor 218, for example, can organize raw data received from the sensing elements 204, 206 into such a format. The vertical axis 406 (ordinate) of the upper graph 402 indicates ambient relative humidity and the horizontal axis 406 (abscissa) represents time. The upper graph 402 provides an indication of how the ambient relative humidity that a set of associated electronic components was exposed to varied over time. The points 404 on the graph indicate actual samplings of relative humidity. In order to maximize accuracy of the graph to most closely represent actual ambient conditions it may be desirable to reduce the time between sample points 404. However, doing so may hasten the depletion of available memory in the environmental condition recorder 202.

The vertical axis 410 (ordinate) of the lower graph 412 indicates ambient temperature and the horizontal axis 414 (abscissa) represents time. The lower graph 412 provides an indication of how the ambient temperature that a set of associated electronic components was exposed to varied over time. The time axis 414 of the lower graph is the same as the time axis of the upper graph 408. So it is possible to estimate both the ambient relative humidity and the ambient temperature at any point along the illustrated time axes. Such information can be used to determine the ambient moisture content that the associated set of electronic components was exposed to at each point along the illustrated axes. The information illustrated in the graphs may be outputted from an environmental condition recorder 202 to a remote device 214 or may be stored in a memory storage unit 210 of the environmental condition recorder 202 for local processing.

With reference to the flowchart of FIG. 6A, a processor receives 502 data, for example graphical data representing recorded relative humidity values and recorded temperature values

associated with a set of electronic components over time. The received data provides an indication of ambient moisture content variation over time. As outlined above, the processor may be part of a remote device or may be integral to an environmental condition recorder. If the processor is remotely located the data can be received over a communications channel such as an RS232 connection or a wireless connection. If the processor is integral with the environmental condition recorder 202A the data can be read directly from the memory storage unit 210A.

The processor can identify 504 a reference time to start calculating a remaining floor life of the associated set. This reference time can be, for example, associated with a time that remaining floor life is assumed to be undiminished and can be used as a baseline for calculating subsequent decrements to remaining floor life. This reference time may be identified by applying an algorithm to the received graphical data to identify a time that the set of electronic components had been exposed to drying conditions, that is a temperature and/or relative humidity above a predetermined value for a predetermined length of time to effectively reset the remaining floor life to 100%. Alternatively, the reference time can be the time associated with the first or last measured data values. For illustrative purposes, it can be assumed that the reference time period corresponds to the first measured set of data values.

The processor initializes 506 a counter representative of a total remaining floor life, for example, by setting the value in the counter to 100%. In one implementation, this value in the counter is a percentage that represents a remaining floor life. The counter can be decremented for each reduction of floor life the associated set of electronic components experiences. In a particular implementation, each set of temperature and relative humidity measurements recorded by the environmental condition recorder 202 indicates a quantity of moisture present in the ambient environment. If the quantity of moisture exceeds a particular value, the total remaining

floor life is reduced. If the quantity of moisture is below a certain value, the total remaining floor life is increased. If the value in the total remaining floor life counter reaches 0%, the remaining floor life associated with the set of electronic components is assumed to be 0%. If the value in the total remaining floor life counter is 100%, the remaining floor life associated with the set of electronic components is assumed to be 100%.

The processor considers 508 a set of data points, for example data points representative of the first recorded time period and determines 510 whether the data indicates a baking condition. Environmental parameters identifying a baking condition can be based on industry standard information. A baking condition can be indicated, for example, by a specific combination of temperature and relative humidity values that may result in a drying effect applied to the associated electronic components.

If the processor determines 510 that a drying or baking event is not represented by the data, the processor calculates 522 a decrease in floor life. Such a calculation can be based on industry available standards or other guidelines. The processor then decrements 524 the total remaining floor life counter an appropriate amount, based on the calculation. The total remaining floor life counter should be configured to store only values between 0% and 100%. Any attempts to increment or decrement the value stored in the counter to outside that range should be ignored.

If the processor determines 510 that a drying or baking event occurred, the processor then determines 512 whether the baking cycle is complete. A baking cycle can be considered complete if, for example, the value in the total remaining floor life counter is equal to 100%. Additionally, industry standard practices provide guidelines detailing criteria for completing a

baking cycle. If the baking cycle is completed, the processor sets 514 the value in the remaining floor life counter to 100%.

If the processor determines 512 that the bake cycle is not complete, the processor calculates 516 an increase in remaining floor life based on the data associated with the time period being considered. Such a calculation can be made by using industry standard guidelines. The processor then increments 518 the value in the total remaining floor life counter an amount equal to the calculated increase in floor life. The maximum allowable value to be stored in the total remaining floor life counter is 100%. Any attempt to increment the value beyond this amount should be ignored.

Next, the processor determines 520 whether all recorded data has been considered. If the processor determines 520 that all recorded data has not been considered, the processor repeats the steps outlined above for data associated with the next recorded time period. If the processor determines 520 that all data has been considered, the processor determines 526 whether the value in the total remaining floor life counter is equal to 0%. If the value is equal to 0%, the processor concludes 528 that the associated set of electronic components is not acceptable for installation into an assembly. If the value in the total remaining floor life counter is greater than 0%, the processor concludes 530 that the associated set of electronic components are suitable for installation into an electronic assembly.

FIG. 6B outlines an enhancement of the method described above that might, in certain instances, provide a more rapid determination of suitability for installation of a set of electronic components based on a set of data indicative of ambient moisture content over time.

First, the processor receives 532 data indicative of ambient moisture content over time. The processor initializes 534 the value in the total remaining floor life counter, for example, by

setting the value to 100%. The processor then considers 536 the last recorded time period data set and determines 538 whether the data indicates a baking condition or not. If the processor determines 538 that the data indicates a baking condition, the processor then considers 540 whether the set of electronic components had been exposed to a complete bake cycle, resulting in
5 a complete resetting of floor life. If the set of electronic components had been exposed to a complete bake cycle, the processor concludes 541 that an amount of life is remaining equal to the amount of life indicated by the value in the remaining floor life counter prior to considering the baking condition.

If the processor determines 540 that the bake cycle is not complete, the processor
10 considers 542 data associated with the previous time period. This cycle can continue until the processor determines 540 that the baking cycle is complete or until an uncompleted baking cycle has ended.

If the processor determines 538 that a baking condition is not indicated by a set of data being considered, the processor determines 544 whether the previously considered set of data
15 indicated a baking condition. If the previously considered set of data indicated a baking condition then the electronic components were probably exposed to some limited, but not complete baking cycle. The processor then identifies 504 a reference time period (i.e., the first time period) and proceeds as described above with reference to FIG. 6A.

Referring again to FIG. 6B, if the processor determines 544 that the previous set of data
20 did not indicate a baking, then the processor calculates 546 a decrease in floor life associated with the set of data being considered and decrements 548 the total remaining floor life counter accordingly. The total remaining floor life counter should be configured to store any value

between 0% and 100%. Attempts to decrement the value stored in the counter to less than 0% should be ignored.

The processor then considers 550 whether the value in the total remaining floor life counter is equal to 0%. If the value is 0%, the processor can conclude 552 that the associated set of electronic components is not suitable for installation into electronic assemblies. If the value in 5 the total remaining floor life counter is greater than 0%, the processor determines 554 whether all time recorded time periods have been considered. If all periods have been considered, the processor can conclude 556 an estimated remaining floor life based on the value stored in the total remaining floor life counter. If all time periods have not been considered, the processor can 10 consider 542 data associated with another time period, one time period earlier.

After concluding an estimated floor life or a suitability for installation of the associated electronic components, the processor can output data indicative of its conclusion. The data outputted by the processor can be stored in a memory storage device, displayed on a screen, used to illuminate a light emitting diode or can be transmitted to an automatic controller configured to 15 perform specific actions. An automatic controller might, for example, stop a reflow operation in response to data indicating a low remaining floor life associated with a set of electronic components.

FIG. 7 shows an excerpted table 602 from IPC/JEDEC J-Std-033 Joint Industry Standard, April 1999 that includes information that, depending on the specific system architecture, could 20 be stored either in a local memory storage unit, such as 210A or in a remote memory storage unit such as 220. A processor could use the information included in the table 602 to estimate reductions in remaining floor life.

The table 602 provides equivalent derated floor lives (measured in days) applicable to various electronic components exposed to environmental relative humidity values 604 ranging from 20-90% RH and temperatures 606 of 20°C, 25°C and 30°C. The table 602 is specifically applicable to SMDs, molded with novolac, biphenyl or multifunctional epoxy mold compounds, however, similar information is available for use with other technologies and materials. The table 602 also indicates that the body thickness 608 and the moisture sensitivity level (M.S. Level) 610 of electronic components can influence its associated total equivalent floor life. These variables are dependent on specific characteristics of each set of electronic components. This information indicating the body thickness 608 and the moisture sensitivity level 610 can be programmed into an associated environmental condition recorder 202 for automatic reading.

FIG. 8 provides a second excerpted table 802 from IPC/JEDEC J-Std-033 Joint Industry Standard, April 1999 that includes information that also can be stored in a memory storage unit, such as 210A. The processor also could use the information included in the table 802 to identify baking events that a set of electronic components were exposed to.

The information details component-drying conditions. If the processor identifies a period of time in recorded data that satisfies the conditions described in the table 802, it can be assumed that degradation of floor life began after that period.

The data included in the table 802 can be used to derive an estimation of an increase in the estimated floor life associated with a set of electronic components.

FIG. 9 provides a specific graphical representation of environmental condition measurements taken over time period of four days for an associated set of electronic components. The graphical representation can be used to illustrate the concepts discussed above. The upper graph 702 indicates relative humidity measurements taken over time and the lower

graph 704 indicates temperature measurements taken over time. The time units are indicated on the horizontal axis as days. Data similar to this may be outputted from an environmental condition recorder 202 for further processing by a remote device or may be further processed by an integral processor in the environmental condition recorder 202.

5 The processor first receives the graphical data and data indicating the body thickness and the moisture sensitivity level of the electronic components of the subject set. All of this data can be read from an environmental condition recorder 202. For illustrative purposes, it can be assumed that the data indicates a body thickness of 2.5 millimeters and a moisture sensitivity 610 of Level 4. The processor then initializes an associated remaining floor life counter by setting
10 the value in the counter to 100%.

 The processor considers the set of data corresponding to the last recorded period of time. The processor determines that the environmental condition (i.e., a temperature of 30° and a relative humidity of 20%) does not represent a baking condition. The processor also considers whether a partial baking event may have occurred. The processor does this by considering
15 whether a baking condition is indicated by a set of data in a later time period than the time period being considered.

 Next, the processor calculates a reduction in floor life during the period of time associated with the last set of data points, which is the period from the day 3 to day 4. During that period, the data indicates a temperature of 30°C and a relative humidity of 20%. The
20 processor can refer to information stored in the memory storage unit based on table 602 and determine that the equivalent total floor life under such an environmental condition is 5 days. Since the length of the associated time period is 1 day, the processor can determine that the floor
25 life reduction factor associated with the last time period is equal to 1 day/5 days or 20%. The

processor decrements the value stored in the total remaining floor life counter by 20%. The stored value is then 80%.

Since the value in the total remaining floor life counter is not equal to 0%, and all recorded time periods have not been considered, the processor considers data points
5 corresponding to the previous time period. The previous set of data also does not represent a baking condition. The processor calculates the floor life reduction factor associated with the data, from day 2 to day 3. During that period, the data indicates a temperature of 30°C and a relative humidity of 30%. Referring to the stored data corresponding to the data of table 602, the equivalent total floor life for the electronic components under this environmental condition is 4
10 days. The length of time associated with this period is 1 day. Therefore, the floor life reduction associated with that time period can be estimated as 1 day/4 days, or 25%. The processor then decrements the total remaining floor life counter by 25% so the value is then 55%.

Since the value stored in the total remaining floor life counter is not less than 0%, all of the relevant time periods still have not been considered, and the data points of the previous time
15 period do not represent a baking event, the processor estimates the floor life reduction factor during the previous period from day 1 to day 2. During that time, the data indicates a temperature of 25°C and a relative humidity of 50%. Referring again to the data of table 602, the equivalent total floor life for the electronic components under this environmental condition is 4
days. Accordingly, the processor determines that 25% of floor life expired over the one day time
20 period under these conditions. The processor then decrements the total remaining floor life counter an additional 25% to 30%.

Once again, the total floor life reduction factor still is not equal to 0%, all of the relevant time periods have not yet been considered and the data points associated with previous period do

not indicate the occurrence of a baking event. The processor calculates a reduction in floor life from day 0 to day 1. During that time period, the data indicates a temperature of 30°C and a relative humidity of 20%. Referring again to the data of table 602, the equivalent total floor life for the electronic components under this environmental condition is 5 days. Accordingly, the processor determines that 20% of floor life is depleted over the one day time period under such conditions. The processor then decrements the value stored in the total remaining floor life counter an additional 20% to 10%.

The value stored in the total remaining floor life counter is still not equal to 0%, however, all of the relevant time periods have been considered. Therefore, the processor concludes that 10% floor life is remaining for the associated set of electronic components.

The processor can compare the value of 10% with a minimum acceptable value or it can be further processed to convert the percentage of remaining floor life to an amount of floor life remaining expressed in days or hours under specified environmental conditions. For example, if the electronic components discussed above are expected to be stored in an environment of 20% relative humidity and 30°C for 6 hours (0.25 days), referring again to table 602, the total additional degradation of floor life can be estimated as $0.25 \text{ days} / 5 \text{ days} = 5\%$. This may or may not be considered acceptable.

Various features of the techniques described can be modified. For example, the environmental condition sensors can be configured to communicate with a reflow machine to either allow or disallow reflow to occur based on an evaluation of the recorded data. Other standards and guidelines for estimating remaining floor life can be implemented. Other data, such as part numbers and serial numbers, related to an associated set of electronic components can be stored in the memory storage unit 210 of the environmental condition recorder 202. The

processor 208 might be capable of formatting the collected data into other formats, such as a histogram. The processor 208 might be configured to go into a "sleep mode" between sampling times, this can extend the life of a battery supplying power to the environmental condition recorder 202. The memory storage unit 210 of the environmental condition recorder 202 can be erasable and reusable.

Various features of the system can be implemented in hardware, software or a combination of hardware and software. For example, some features of the system can be implemented in computer programs executing on programmable computers. Each program can be implemented in a high level procedural or object oriented programming language to communicate with a computer system. Furthermore, each such computer program can be stored on a storage medium, such as read-only-memory (ROM) readable by a general or special purpose programmable computer or processor, for configuring and operating the computer when the storage medium is read by the computer to perform the functions described above.

A number of implementations of the invention have been described. Nevertheless, it will be understood that various modifications may be made without departing from the spirit and scope of the invention. Accordingly, other implementations are within the scope of the following claims.

What is claimed is:

1. A method of evaluating a set of identical electronic components prior to installing the components into electronic assemblies, the method comprising:

collecting (102) data indicative of an environmental condition associated with the electronic components during consecutive periods of time prior to installing the electronic components from the set into the electronic assemblies;

storing (104) the collected data;

evaluating (106) whether the electronic components are suitable for installation based on an estimated cumulative effect of exposure to the environmental condition based on the stored data; and then, for electronic components found suitable for installation,

installing the suitable electronic components into electronic assemblies.

2. The method of claim 1 wherein collecting (102) the data indicative of the environmental condition comprises sensing atmospheric moisture content.

3. The method of claim 2 wherein sensing atmospheric moisture content comprises measuring ambient temperature and measuring relative humidity.

4. The method of any of the above claims wherein evaluating (106) whether the electronic components are suitable for installation comprises:

estimating a remaining floor life associated with the electronic components by calculating a floor life reduction value associated with each consecutive period of time; and

determining a total remaining floor life value based on the floor life reduction values associated with each consecutive period of time.

- 5 5. The method of claim 4 wherein estimating the remaining floor life comprises identifying a reference time associated with a reference remaining floor life value.
6. The method of claim 5 wherein the reference time is identified as a time that collecting data indicative of the environmental condition was initiated.
- 10 7. The method of claim 5 or claim 6 wherein the reference time is identified based on a time that a baking event occurred.
8. The method of any of claims 5 through 7 wherein the reference time is identified based on a time that the electronic components experienced a prolonged exposure to a temperature
15 greater than a preset temperature.
9. The method of any of claims 5 through 8 wherein the reference time is identified as a time that a final set of data was collected.
- 20 10. The method of any of claims 4 through 9 wherein estimating the remaining floor life comprises:
 - accounting for a moisture sensitivity level with the set of electronic components; and
 - accounting for a body thickness associated with the electronic components.

11. The method of any of the above claims wherein evaluating whether the electronic components are suitable for installation comprises integrating a set of sensed moisture content values over time to calculate a cumulative environmental exposure factor.

5

12. The method of any of the above claims wherein evaluating whether the electronic components are suitable for installation comprises comparing the estimated cumulative effect of exposure to the environmental condition to a predefined acceptance criteria to determine an estimated reliability factor.

10

13. A container of electronic components to be installed into electronic assemblies, the container comprising:

a storage device (304, 322, 326) containing a set of electronic components; and

an environmental condition recorder (202, 202a) coupled to the storage device (304, 322,

15 326) and associated with the set of electronic components, the environmental condition recorder (202, 202a) comprising sensing elements (204, 206) responsive to an ambient environmental condition, a processor (208, 208a) and an associated memory storage device (210, 210a), the processor (208, 208a) being configured to receive data from the sensing elements (204, 206) indicative of the ambient environmental condition during multiple, successive periods of time, to
20 cumulatively and accessibly store the data in the associated memory storage device (210, 210a) and to evaluate whether the electronic components are suitable for installation based on a cumulative effect of exposure to the ambient environmental condition.

14. The container of claim 13 wherein the storage device (304, 322, 326) comprises a reel (304) containing multiple identical electronic components.

15. The container of claim 13 or claim 14 wherein the sensing elements (204, 206) are responsive to ambient moisture content.

16. The container of any of claims 13 through 15 wherein the processor (208, 208a) is further configured to create a graphical representation of the data plotted against an axis representative of time.

10

17. The container of any of claims 13 through 16 wherein the environmental condition recorder (202, 202a) further comprises a timing element (212) and wherein the processor (208, 208a) receives and stores the data at predefined intervals of time as measured by the timing element (212).

15

18. The container of any of claims 13 through 17 wherein the processor (208, 208a) is further configured to communicate the stored data and a determination of whether the electronic components are suitable for installation to a remote device (214).

19. The container of any of claims 13 through 18 wherein the processor (208, 208a) is further configured to estimate a remaining floor life associated with the electronic components.

20. The container of any of claims 13 through 19 wherein the processor (208, 208a) is further configured to identify a reference time associated with a reference remaining floor life value.

21. The container of any of claims 13 through 20 wherein the processor (208, 208a) is further
5 configured to calculate a reduction in floor life associated with each of multiple, consecutive periods of time and to calculate a cumulative total remaining floor life based on the calculated reductions in floor life associated with each consecutive period of time.

22. The container of claim 19 wherein estimating the remaining floor life comprises
10 considering a moisture sensitivity level associated with the set of electronic components and a body thickness associated with each electronic component of the set.

23. The container of any of claims 13 through 22 wherein the processor (208, 208a) is further
15 configured to integrate a set of sensed ambient moisture content values over time to calculate a cumulative environmental exposure factor.

24. The container of any of claims 13 through 23 wherein the processor (208, 208a) is further
configured to compare the data to a predefined baseline to determine an estimated reliability
factor.

25. A system for evaluating a set of identical electronic components prior to installing the
20 components into electronic assemblies, the system comprising:

a storage device (304, 322, 326) containing a set of identical electronic components;

an environmental condition recorder (202, 202a) coupled to the storage device (304, 322, 326) and associated with the set of identical electronic components, the environmental condition recorder (202, 202a) configured to collect data indicative of an environmental condition over multiple, successive periods of time; and

5 a remote device (214) comprising a processor (218) and a memory storage unit (220), wherein the processor (218) is configured to receive the collected data from the environmental condition recorder (202, 202a) and evaluate whether the electronic components are suitable for installation based on the collected data.

10 26. The system of claim 25 wherein the processor (218) is further configured to estimate a remaining floor life associated with the set of electronic components.

27. The system of claim 25 or claim 26 wherein the processor (218) is further configured to calculate a reduction in floor life associated with each of the multiple, successive periods of time and to calculate a total remaining floor life based on the calculated reductions in floor life
15 associated with each of the multiple, successive periods of time.

28. The system of claim 26 wherein estimating the remaining floor life comprises considering a moisture sensitivity level associated with the electronic components of the set and
20 a body thickness value associated with the electronic components of the set.

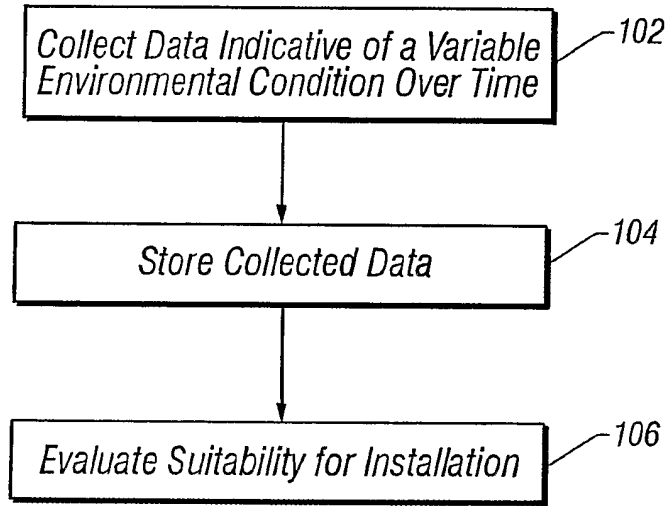


FIG. 1

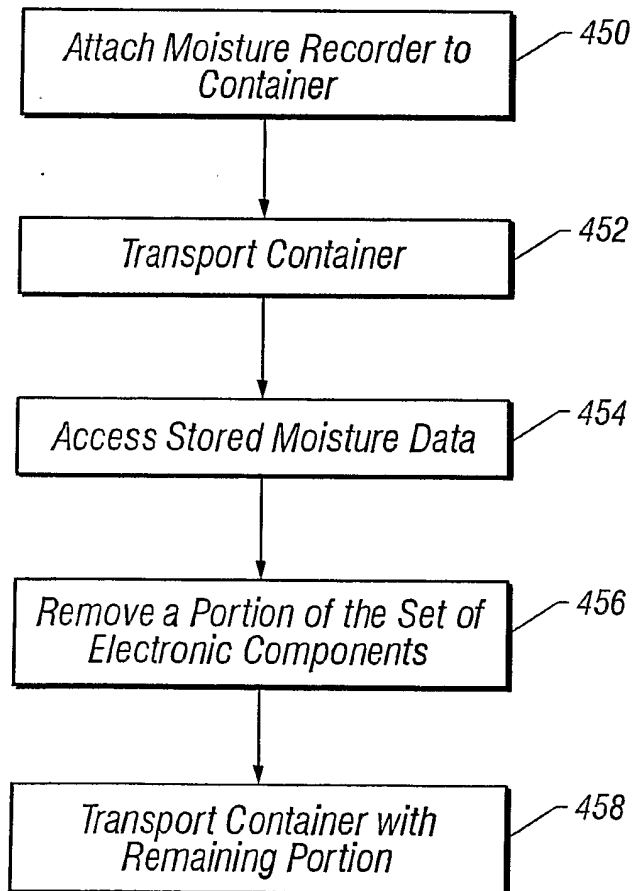


FIG. 4

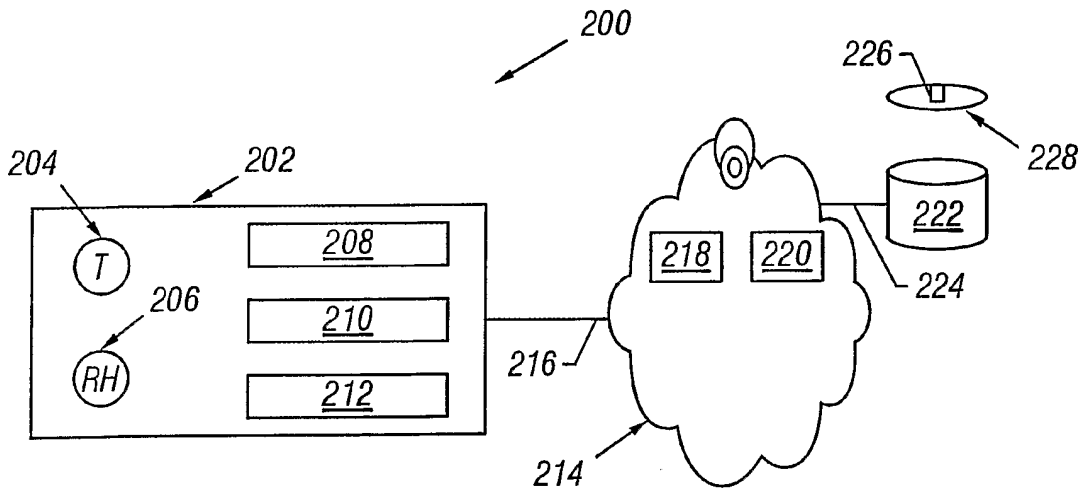


FIG. 2A

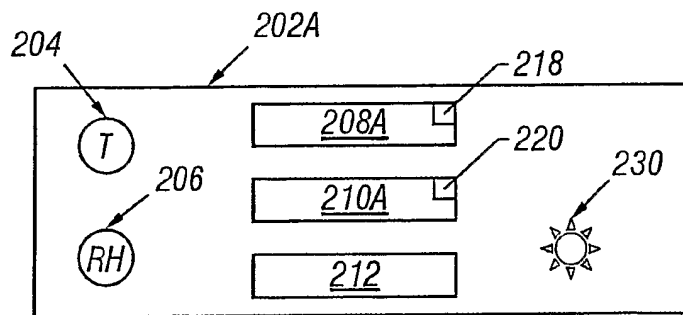


FIG. 2B

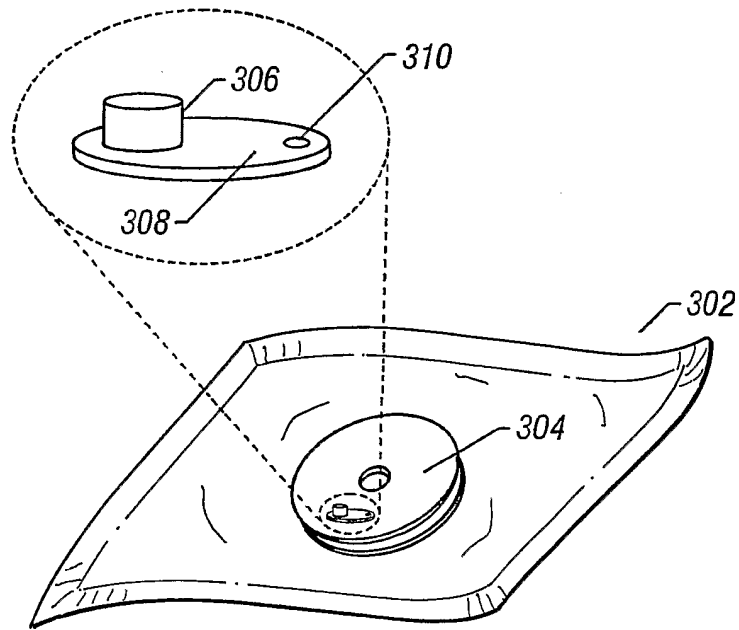


FIG. 3A

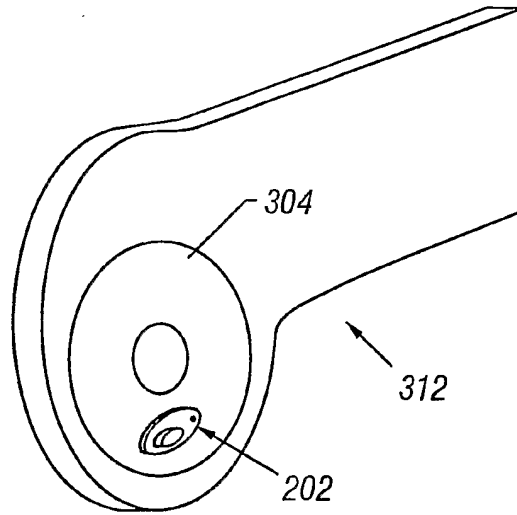


FIG. 3B

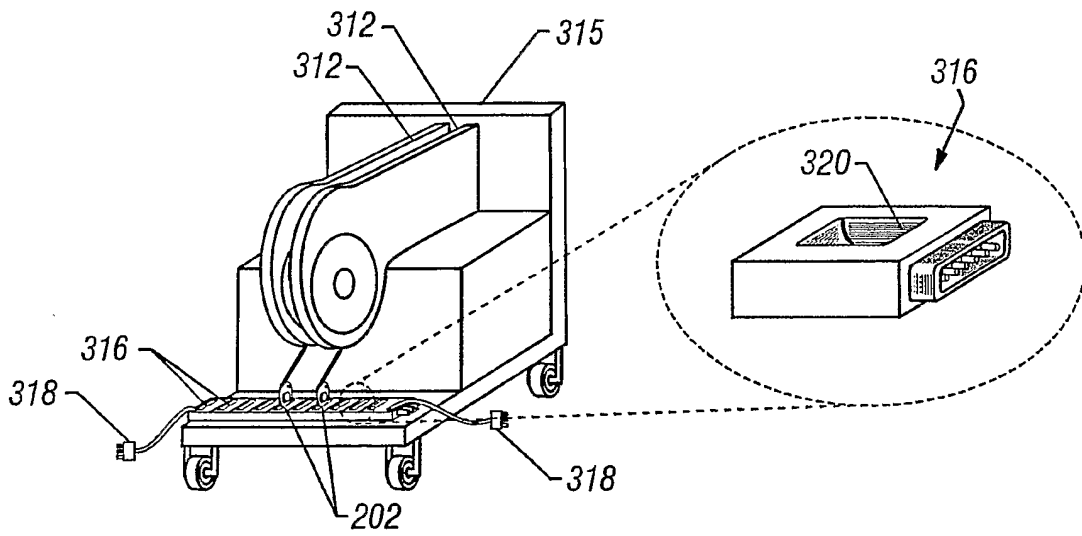


FIG. 3C

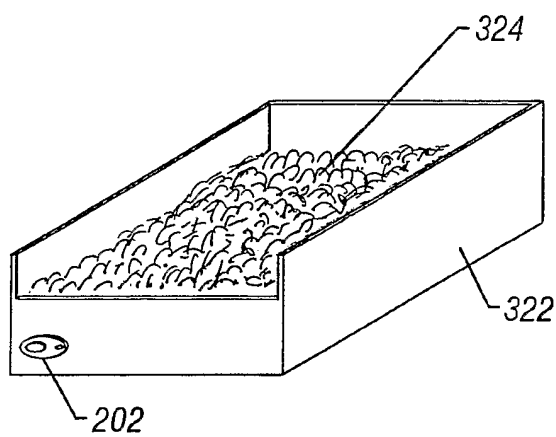


FIG. 3D

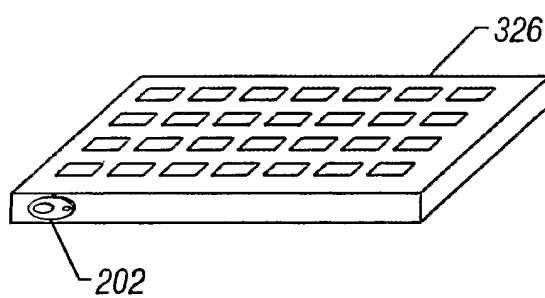


FIG. 3E

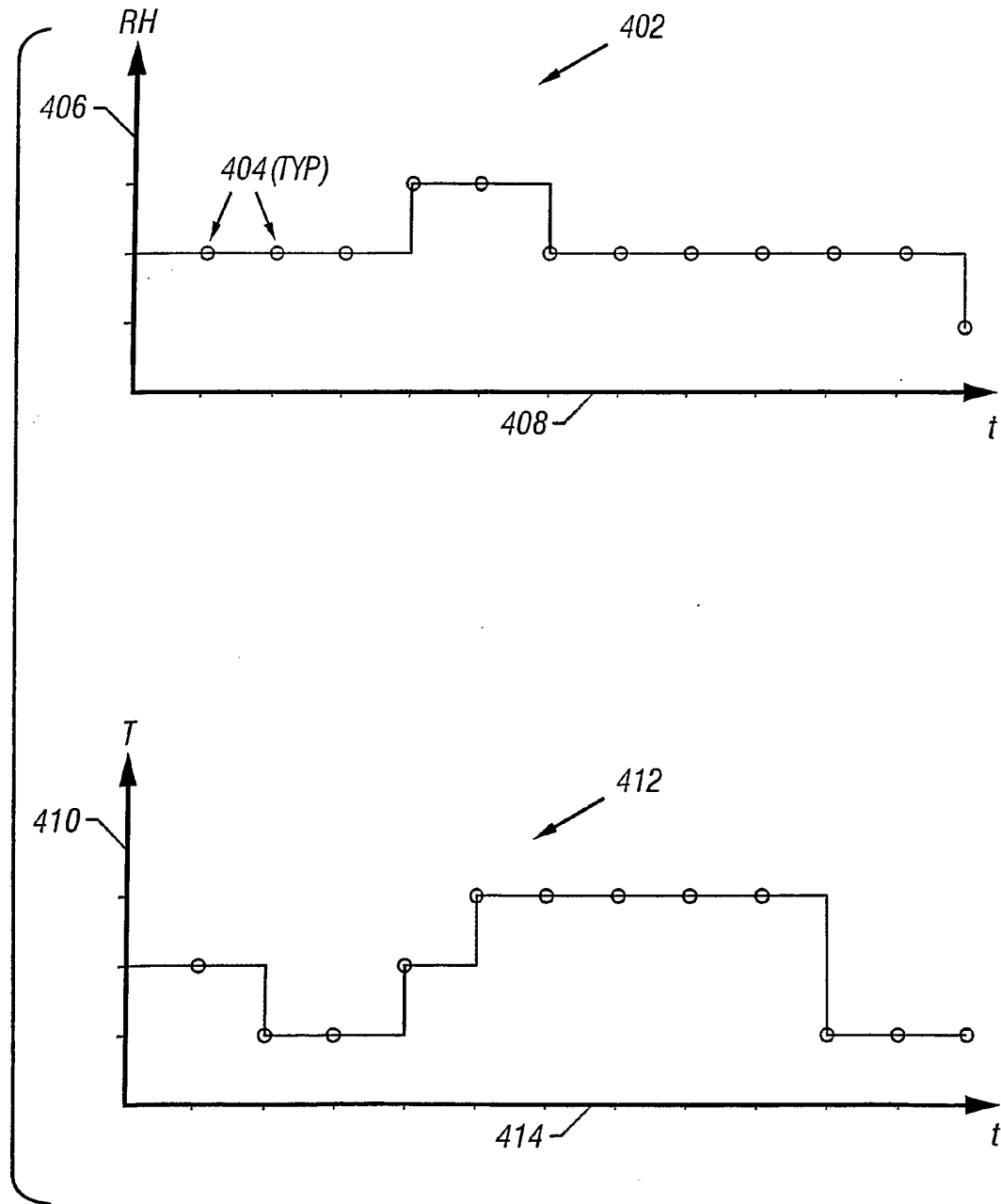


FIG. 5

7/11

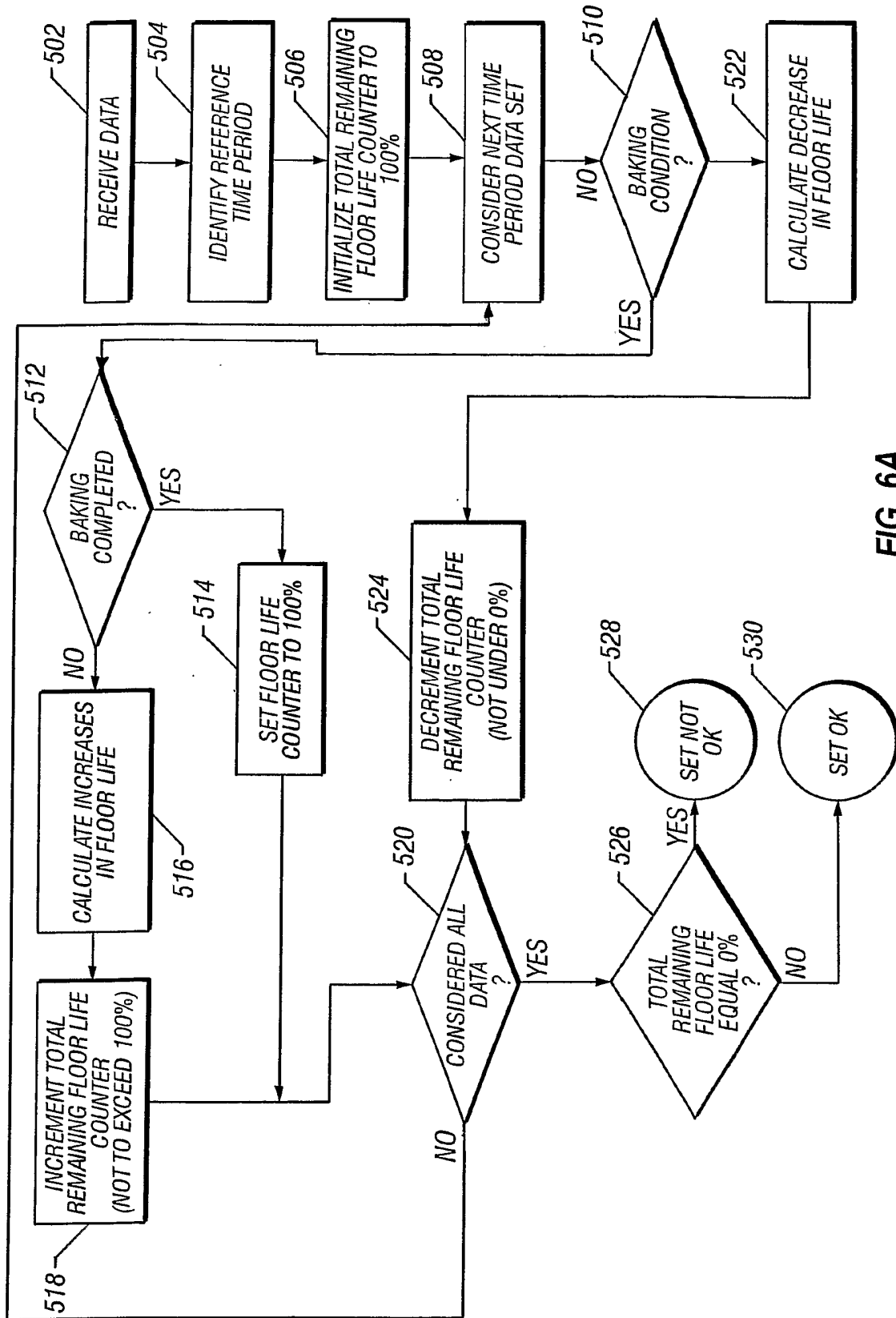


FIG. 6A

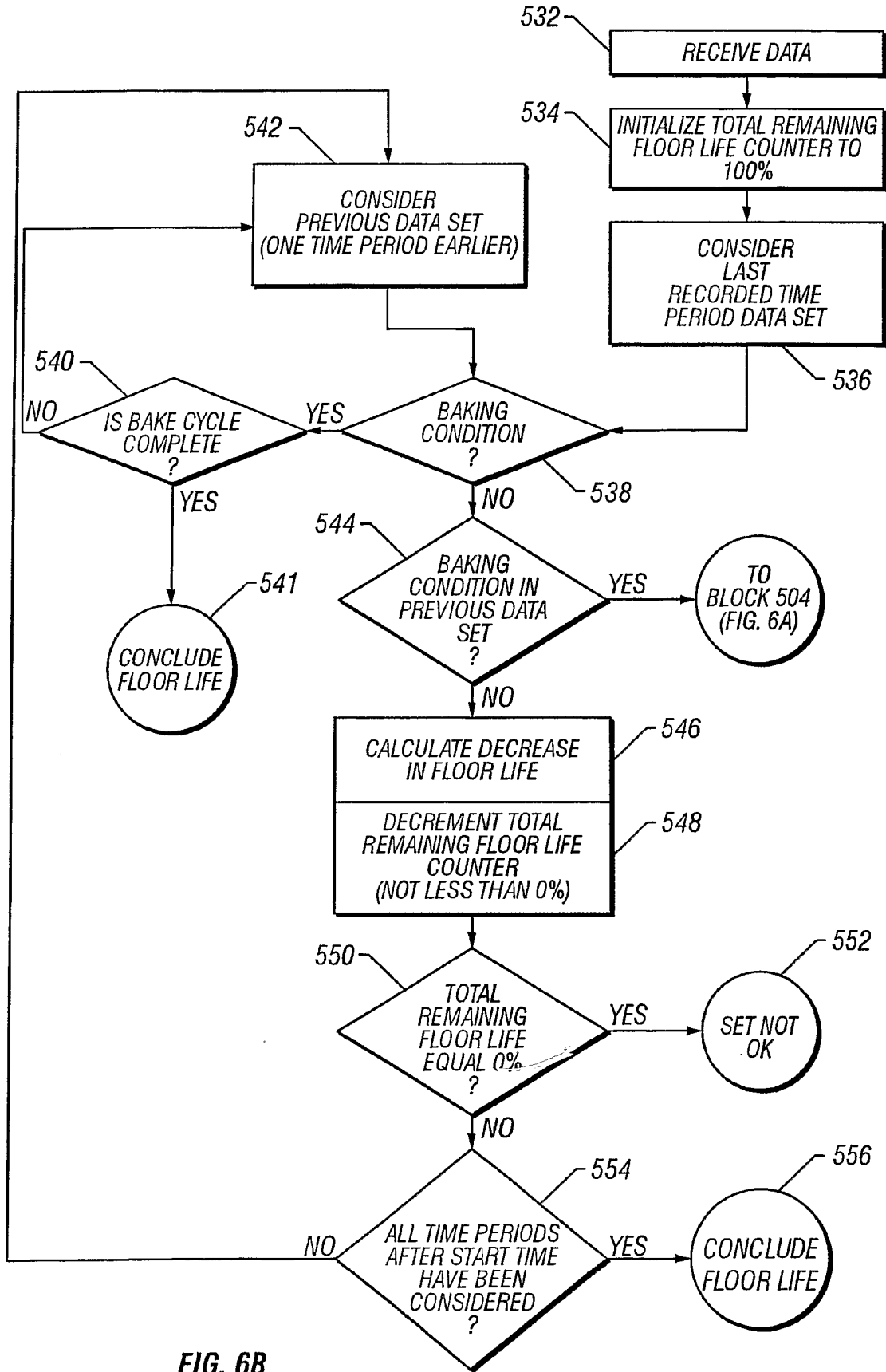


FIG. 6B

IPC/JEDEC J-STD-033		April 1999									
TABLE 5 Recommended Equivalent Total Floor Life (days) @ 20°C, 25°C & 30°C For ICs with Novolac, Biphenyl and Multifunctional Epoxies (Reflow at same temperature at which the component was classified)											
Body Thickness (t)	M.S.Level	Maximum Percent Relative Humidity									
		20%	30%	40%	50%	60%	70%	80%	90%		
t > 3.1mm PQFPs > 84 pins. PLCCs (square) MQFPs or PBGAs	Level 2a	∞	60	41	33	28	10	7	6	30°C	
		∞	78	53	42	36	14	10	8	25°C	
		∞	103	69	57	47	19	13	10	20°C	
	Level 3	10	9	8	7	7	5	4	4	30°C	
		13	11	10	9	9	7	6	5	25°C	
		17	14	13	12	12	10	8	7	20°C	
	Level 4	4	4	4	3	3	3	2	2	30°C	
		5	5	5	5	4	3	3	3	25°C	
		7	7	7	7	6	5	4	4	20°C	
	Level 5	3	3	2	2	2	2	1	1	30°C	
		5	4	4	3	3	2	2	2	25°C	
		7	6	5	5	4	3	3	3	20°C	
	Level 5a	1	1	1	1	1	1	1	1	30°C	
		2	2	2	2	2	1	1	1	25°C	
		4	3	3	3	2	2	2	2	20°C	
t < 2.1mm t < 3.1mm PLCCs (rectangular) 18-32 pins SOICs (wide body) SOICs ≥ 20 pins PQFPs ≤ 80 pins	Level 2a	∞	∞	86	39	28	4	3	2	30°C	
		∞	∞	148	51	37	6	4	3	25°C	
		∞	∞	∞	69	49	8	5	4	20°C	
	Level 3	19	12	9	8	7	3	2	2	30°C	
		25	15	12	10	9	5	3	3	25°C	
		32	19	15	13	12	7	5	4	20°C	
	Level 4	5	4	4	3	3	2	2	1	30°C	
		7	5	5	4	4	3	2	2	25°C	
		9	7	6	6	5	4	3	3	20°C	
	Level 5	3	3	2	2	2	1	1	1	30°C	
		4	3	3	3	3	2	1	1	25°C	
		5	5	4	4	4	3	3	2	20°C	
	Level 5a	1	1	1	1	1	1	0.5	0.5	30°C	
		2	2	2	2	2	1	1	1	25°C	
		2	2	2	2	2	2	2	1	20°C	
t > 2.1mm TSOPs, SOICs < 18 pins TQFPs or or TBGAs	Level 2a	∞	∞	∞	∞	28	1	1	1	30°C	
		∞	∞	∞	∞	∞	2	1	1	25°C	
		∞	∞	∞	∞	∞	2	2	1	20°C	
	Level 3	∞	∞	∞	11	7	1	1	1	30°C	
		∞	∞	∞	14	10	2	1	1	25°C	
		∞	∞	∞	20	13	2	2	1	20°C	
	Level 4	∞	9	5	4	3	1	1	1	30°C	
		∞	12	7	5	4	2	1	1	25°C	
		∞	17	9	7	6	2	2	1	20°C	
	Level 5	13	5	3	2	2	1	1	1	30°C	
		18	6	4	3	3	2	1	1	25°C	
		26	8	6	5	4	2	2	1	20°C	
	Level 5a	3	2	1	1	1	1	1	0.5	30°C	
		5	3	2	2	2	1	1	1	25°C	
		6	4	3	2	2	2	2	1	20°C	

FIG. 7
(Prior Art)

604

802
↙

<i>Package thickness</i>	<i>Level</i>	<i>Bake@125°C</i>	<i>Bake@40°C ≤5%RH</i>
<i>≤1.4 mm</i>	<i>2a</i>	<i>4 hours</i>	<i>5 days</i>
	<i>3</i>	<i>7 hours</i>	<i>11 days</i>
	<i>4</i>	<i>9 hours</i>	<i>13 days</i>
	<i>5</i>	<i>10 hours</i>	<i>14 days</i>
	<i>5a</i>	<i>14 hours</i>	<i>19 days</i>
<i>≤2.0 mm</i>	<i>2a</i>	<i>18 hours</i>	<i>21 days</i>
	<i>3</i>	<i>24 hours</i>	<i>33 days</i>
	<i>4</i>	<i>31 hours</i>	<i>43 days</i>
	<i>5</i>	<i>37 hours</i>	<i>52 days</i>
	<i>5a</i>	<i>48 hours</i>	<i>68 days</i>
<i>≤4.0 mm</i>	<i>2a</i>	<i>48 hours</i>	<i>67 days</i>
	<i>3</i>	<i>48 hours</i>	<i>67 days</i>
	<i>4</i>	<i>48 hours</i>	<i>68 days</i>
	<i>5</i>	<i>48 hours</i>	<i>68 days</i>
	<i>5a</i>	<i>48 hours</i>	<i>68 days</i>

Table 2 Reference Conditions for Drying Components that were Exposed to Conditions ≤60% RH (User Bake:Floor Life Begins Counting at Time=0 after bake)

FIG. 8
(Prior Art)

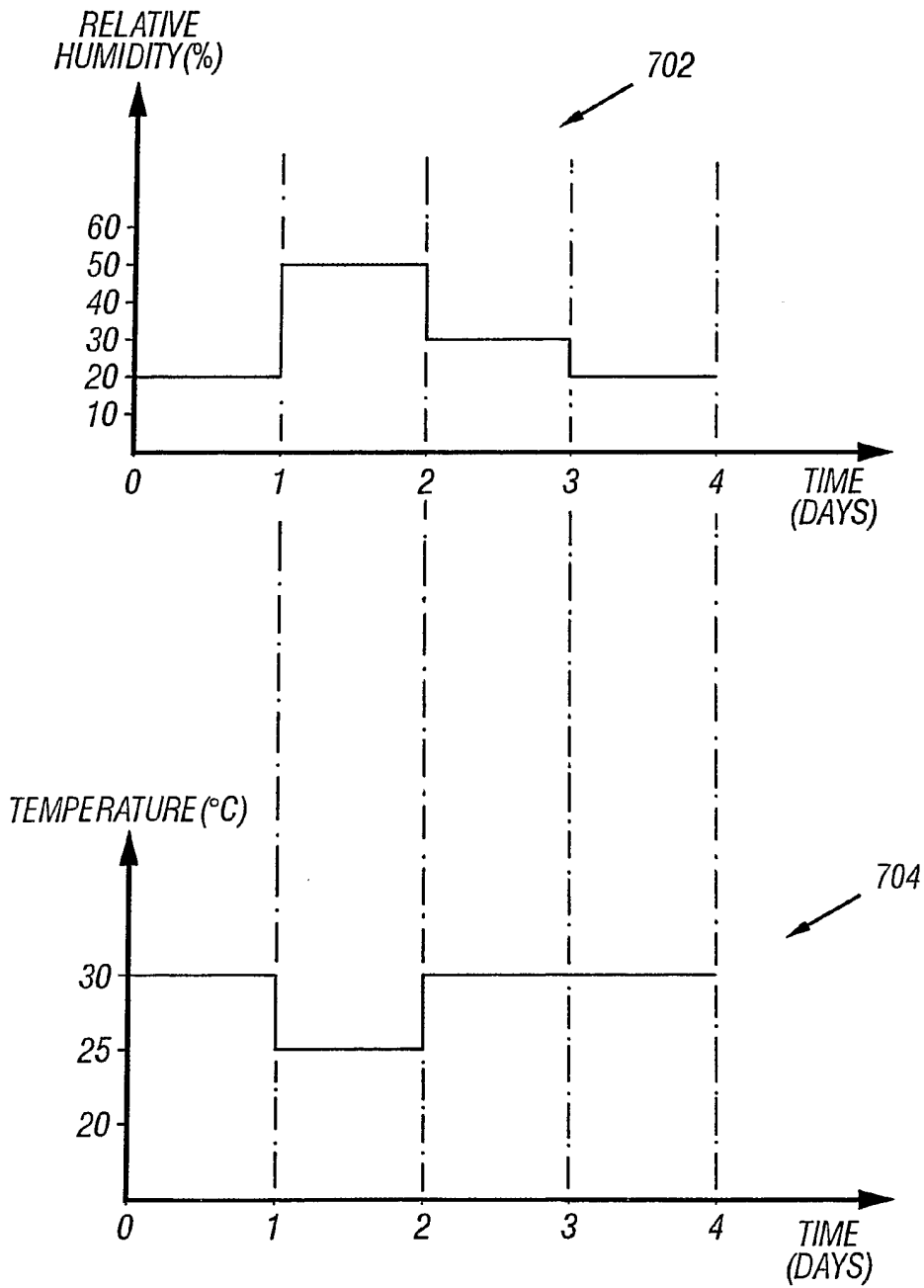


FIG. 9